
IN THE DETAILED DESCRIPTION SECTION

Please amend the specification by replacing the paragraph on page 6, beginning at line 9, with the following paragraph.

After the carbon-based cladding 26, 32 [[34]] associated with the dielectric board member 24 has been appropriately fashioned, one or more additional board layers may be added to the PCB structure. The additional layers can include normal PCB layers or cladding-modified layers as described above. In one approach, via connections and/or plated through-holes are used to provide signal communication between the layers. One or more additional photolithography steps may also be performed on the upper board layer to expose portions of the metallization thereon to act as standard surface mount pads. The deposition of the carbon-based cladding and the metal layers on the PCB may be done in either an additive or a subtractive process.